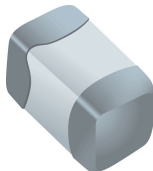


MATERIAL DECLARATION SHEET



Material Number	SF-0402SxxxM			
Product Line	Lead Free Multilayer Solid Matrix Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	0.5275	Boron	7440-42-8	7.39%	5.16%	69.7844%
				Carbon	7440-44-0	2.11%	1.47%	
				Aluminum	7429-90-5	18.65%	13.01%	
				Silicon	7440-21-3	15.24%	10.63%	
				Potassium	7440-09-7	0.53%	0.37%	
				Oxygen	7782-44-7	56.08%	39.13%	
2	Termination	Silver with Glass	0.1441	Silver	7440-22-4	92.25%	17.58%	19.0634%
				Oxygen	7782-44-7	2.23%	0.43%	
				Zinc	7440-66-6	1.64%	0.31%	
				Silicon	7440-21-3	0.10%	0.02%	
				Bismuth	7440-69-9	3.78%	0.72%	
3	Fuse Link	Silver	0.0054	Silver	7440-22-4	100%	0.7144%	0.7144%
4	Plating	Nickel	0.0789	Nickel	7440-02-0	100.00%	4.68%	10.4378%
		Tin		Tin	7440-31-5	100.00%	5.75%	
Total weight			0.7559					

This Document was updated on: 8-30-17

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.